

## Thermal RC network (Foster)

## SPICE thermal model

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
₹ <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base		-	-	0.57	K/W
	Cth <sub>1</sub>	1.835E-04 F		Д		
	Cth <sub>2</sub>	1.308E-03 F		<b>_</b>	tj	
	Cth <sub>3</sub>	9.881E-04 F				
	Cth <sub>4</sub>	3.804E-03 F			$Rth_1 = Cth_1$	
	Cth <sub>5</sub>	1.211E-02 F				
	Cth <sub>6</sub>	2.411E-02 F				
	Cth <sub>7</sub>	5.977E-01 F		- Г	<b>└ •</b> _ ]	
	Cth <sub>8</sub>	1.623E+02 F			$\int Rth_2 \stackrel{\bullet}{=} Cth_2$	
	Rth <sub>1</sub>	4.855Ε-04 Ω				
	Rth <sub>2</sub>	9.542E-04 Ω		г	<b>-</b>	
	Rth <sub>3</sub>	1.131E-02 Ω			Rth3 🛨 Cth3	
	Rth <sub>4</sub>	2.702E-02 Ω			ᡗ᠊᠊ᡨ᠁	
	Rth₅	9.606E-02 Ω			<b>\</b>	
	Rth <sub>6</sub>	3.569E-01 Ω			Rth4 Cth4	
	Rth <sub>7</sub>	8.813E-02 Ω				
	Rth <sub>8</sub>	1.348Ε-03 Ω	(	(P)		
						i
					Rth6 $=$ Cth6	i
Dente						
Part:	BUK768R1-100E					1
Date: Nodel Rth	11/4/2013 0.58 K/W					
	0.36 NW			↓ ↓	t <sub>amb</sub> 001aal768	•

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